

GUIDELINES FOR ROHS COMPLIANT COMPONENTS

Procedure Number : N/A Issue# : N/A Issue Date : N/A

1.0 BACKGROUND:

- This document is intended to provide guidelines to lead-free/RoHS compliance.
- RoHS compliance includes materials compliance as well as the process requirements
For lead-free soldering

2.0 LOGISTICS:

- Any component changes related to lead-free/RoHS compliance should be considered major changes.
- Sample Part and qualification data should be available to customers

3.0 COMPATIBILITY:

- A qualification package for lead-free components should be provided that includes the following:
 - Handling, Packing, Shipping and Use (per IPC/JEDEC J-STD-033A)
 - No-clean solder paste and wave solder flux should be included.
- a) For components which go through the reflow process
 - In general, 260°C reflow peak temperature is an overall requirement.
- b) For components (SMD and/or through-hole) which go through the wave soldering process
 - Solder pot temperature: 270°C
 - Contact time: 10s
 - Thermal shock: 130°C
 - Ramp rate: 4°C/S

4.0 PART IDENTIFICATION:

- All components should have the outer packaging boxes and inner package material (tray, tube, and reel) Marked / Labeled (Green) with some form of traceable information indicating that the components are lead-free/RoHS compliant. This marking should also appear on the component package where there is room for such Marking.
- All lead-free/RoHS compliant components should have new supplier P/N's assigned. Suffix or Prefix additions to existing P/N structures are acceptable.
- Device datasheets should clearly indicate the termination solder composition, maximum component Temperature rating recommended & absolute reflow profile limits, and the moisture sensitivity Rating.



5.0 Compliance:

- A “Certificate of RoHS Compliance” with Build-specific data should be submitted with every Build of shipment of RoHS compliant components.